

POS	SPECIFICATION	DOCUMENT#	REMARK
1	Valid for FP-type product family with or without TIM	DRW 0295	Outline drawing FP-type products
2	RoHS compliant		YES
3	Weight		250 g ± 20 g

POS	CONSTRUCTION ELEMENT	MATERIAL GROUP	MATERIALS	CAS-NR IF APPLICABLE	AVERAGE MASS ¹ IN %	COMMENT
1	Chip	Inorganic material	Silicon	7440-21-3	0.1	
2	Baseplate, substrate, incl. metallization	Non noble metal	Copper	7440-50-8	80.1	
3		Inorganic	Aluminum oxide	1344-28-1	1.7	
4		Non noble metal	Tin	7440-31-5	2.4	
5		Noble metal	Silver	7440-22-4		Traces
6		Non noble metal	Nickel	7440-02-0	0.1	Traces
7	Wire	Non noble metal	Aluminum	7429-90-5	0.3	
8	Encapsulation	Polymer	Silicone gel		6	
9		Polymer	Silicon glue		0.1	
10	Housing	Polymer	PBT		7	
11		Inorganic material	Glas fiber		2.3	
18						100

REMARKS

- The information provided is the full declaration of all materials present in SwissSEM product of FP-type product family above a threshold of 0.1% or 1000 ppm.
- All information is according to the best of our knowledge and subject to change at any time for required changes.
- SwissSEM products are not classified as “hazardous substances” according to the definition of EU directive 67/548/EC and do hence not require a Material Safety Datasheet.

DATE	AUTHOR	REMARK
Nov 26th, 2024	SM	Initial Version

¹ Related to component weight

AUTHOR	CHECKED	RELEASED
PL	VP Application and Testing	VP Supply and Quality